

Attorney Docket No. P16677
Application Serial No. 10/665,824

REMARKS

Claims 1-68 were subject to a requirement for restriction. More specifically, the Examiner restricted the claims to a first and second species. The first species is "directed to a method of manufacturing a semiconductor device including the steps of forming a number of vias through a first interconnect structure into a first wafer, depositing an insulating material in each of the number of vias, forming an insulating plug, forming a second interconnect structure over the insulating plug, wherein each of the insulating plugs extends to one of a number of conductors in the second interconnect structure," whereas the second species is "directed to a method of manufacturing a semiconductor device including the steps of depositing an insulating material over a surface of each of the number of vias, forming a second material on the insulating layer in each of the number of vias and wherein the second material in each of the number of vias extends to one of a number of conductors in the second interconnect structure." Office Action, at page 2.

Applicants assert that the first species encompasses claims 1-17 and that the second species encompasses claims 18-68. **Applicants elect claims 1-17 for prosecution in the instant application.**


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CONCLUSION

Applicant respectfully requests entry of this response prior to examination on the merits. Please charge any shortages and credit any overages to Deposit Account No. 02-2666.

Respectfully submitted,

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